

L Number	Hits	Search Text	DB	Time stamp
1	10831	(encapsulant or (encapsulating adj material))	USPAT	2002/09/24 16:16
2	440	((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin)	USPAT	2002/09/24 16:17
3	275	((((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin)) and (bisphenol or phenol\$3 or novola\$2))	USPAT	2002/09/24 16:34
4	161	(((((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin)) and (bisphenol or phenol\$3 or novola\$2)) and (IC or semiconductor or chip))	USPAT	2002/09/24 16:18
5	33	(((((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin)) and (bisphenol or phenol\$3 or novola\$2)) and (IC or semiconductor or chip)) and (dielectric adj constant)	USPAT	2002/09/24 16:19
6	102	(((((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin)) and (bisphenol or phenol\$3 or novola\$2)) and (IC or semiconductor or chip)) and (colorant or pigment or (carbon adj black))	USPAT	2002/09/24 16:19
7	24	((((((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin)) and (bisphenol or phenol\$3 or novola\$2)) and (IC or semiconductor or chip)) and (colorant or pigment or (carbon adj black))) and (dielectric adj constant)	USPAT	2002/09/24 16:20
8	213	((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin)) and ((bisphenol or phenol\$3 or novola\$2) and (epoxy adj resin))	USPAT	2002/09/24 16:34
10	3	(((((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin)) and ((bisphenol or phenol\$3 or novola\$2) and (epoxy adj resin))) and (cavity or opening)) and (embed\$4 near (IC or component or semiconductor or chip or die))	USPAT	2002/09/24 16:39
12	2	((((((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin)) and ((bisphenol or phenol\$3 or novola\$2) and (epoxy adj resin))) and (cavity or opening)) and (embed\$4 near (IC or component or semiconductor or chip or die))) and (dye or (carbon adj black) or pigment or colorant)) and (dielectric adj constant)	USPAT	2002/09/24 16:40
11	3	((((((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin)) and ((bisphenol or phenol\$3 or novola\$2) and (epoxy adj resin))) and (cavity or opening)) and (embed\$4 near (IC or component or semiconductor or chip or die))) and (dye or (carbon adj black) or pigment or colorant)	USPAT	2002/09/24 16:47
9	73	(((((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin)) and ((bisphenol or phenol\$3 or novola\$2) and (epoxy adj resin))) and (cavity or opening))	USPAT	2002/09/24 16:47
13	166	(((((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin)) and (bisphenol or phenol\$3 or novola\$2)) and (dye or (carbon adj black) or pigment or colorant))	USPAT	2002/09/24 16:47

14	34	(((encapsulant or (encapsulating adj material))) and (thermoset\$4 adj resin)) and (bisphenol or phenol\$3 or novola\$2)) and (dye or (carbon adj black) or pigment or colorant)) and (dielectric adj constant)	USPAT	2002/09/24 16:48
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